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Part Number: [0737800247](#)
Status: **Active**
Overview: [HDM® Backplane Connector System](#)
Description: HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 72 Circuits, Mounted Height 17.00mm, Pin Length 3.00mm, Solder Tail

Documents:

[3D Model](#) [Test Summary TS-73670-990 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-73780-999 \(PDF\)](#)

Agency Certification

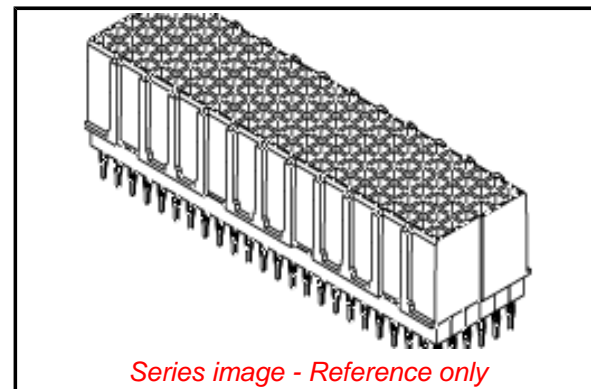
UL E29179

General

Product Family Backplane Connectors
Series [73780](#)
Application Daughtercard, Mezzanine
Comments Solder Tail
Component Type PCB Receptacle
Overview [HDM® Backplane Connector System](#)
Product Name HDM®
UPC 800756378084

Physical

Circuits (Loaded) 72
Circuits (maximum) 72
Color - Resin Black
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Copper-Nickel-Tin
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Net Weight 10.002/g
Number of Columns 12
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length 3.00mm
PCB Locator No
PCB Retention None
PCB Thickness - Recommended 1.60mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 2.540µm
Polarized to PCB No
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55°C to +105°C
Termination Interface: Style Through Hole



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Contains SVHC(2014 December 17): No

Halogen-Free

Status

Low-Halogen

Need more information on product environmental compliance?

Email productcompliance@molex.com
Please visit the [Contact Us](#) section for any non-product compliance questions.

China ROHS

ELV

Green Image

Not Relevant

Search Parts in this Series

[73780](#) Series

Mates With

HDM® Board-to-Board Backplane Header [73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) , [73944](#) , [74349](#) , [74428](#). HDM® Board-to-Board Stacking Header [73769](#) , [73770](#) , [73782](#) , [73783](#) , [73771](#)

Electrical

Current - Maximum per Contact	15.0A, 1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	005
Lead-free Process Capability	WAVE
Max. Cycles at Max. Process Temperature	001
Process Temperature max. C	260

Material Info**Reference - Drawing Numbers**

Product Specification	PS-73780-999
Sales Drawing	SD-73780-004
Test Summary	TS-73670-990

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